# Surface Mount PIN Diode Limiters MLM2060-300 & MLM2060-301 Series Datasheet



#### **Features**

- Surface Mount Limiter in Compact Outline: 8mm L x 5mm W x 2.5 mm H
- Incorporates PIN Limiter Diodes, D.C. Blocks & D.C. Return
- Higher Average Power Handling than Plastic ( 100 W Peak Power )
- Lower Insertion Loss ( 0.85 dB ) & Lower Flat Leakage Power ( 19 dBm )
- RoHS Compliant



#### **Description**

The MLM2060-300 and MLM2060-301 Series of Surface Mount Silicon PIN Diode Limiters is manufactured using Aeroflex-Metelics proven hybrid manufacturing process incorporating PIN Diodes and passive devices integrated within a ceramic substrate. This low profile, compact , surface mount component, ( 8mm L x 5mm W x 2.5 mm H ) offers superior low and high signal performance to comparable MMIC devices in QFN packages. The Limiter Modules are designed to optimize small signal insertion loss, ( N.F.) and high signal flat leakage performance in a compact, surface mount package. The MLM2060-300 has Shunt PIN Limiter Diodes and a Shunt Coil with no D.C. Blocks, whereas the MLM2060-301 incorporates Shunt PIN Limiters Diodes, a Shunt Coil, and D.C. Blocks for versatility of design preference.

Using PIN Diodes with lower thermal resistance ( < 40 °C/W), RF C.W. incident power levels of +36 dBm and RF peak incident power levels of + 50 dBm @ 1  $\mu S$  RF pulse width, 0.001 duty cycle are very achievable in broadband Limiter Applications. The lower PIN Diode series resistance, ( < 1.5  $\Omega$  ), coupled with the smaller minority carrier lifetime, ( < 20  $\eta S$  ), provides lower flat leakage power ( < + 20 dBm ) and lower spike leakage energy ( < 0.1 Ergs ) for superior LNA protection.

## **Applications**

These MLM2060-300 and MLM2060-301 Limiter Series are ideal for 2 to 6 GHz Radar, IED, and WiMax applications, requiring high volume, surface mount, solder re-flow manufacturing. These products are durable, reliable, and capable of meeting all military, commercial, and industrial environments. The devices are fully RoHS compliant and are available in tube or tape-reel.

## **Environmental Capabilities**

The MLM2060-300 and MLM2060-301 Limiter Series is capable of meeting the environmental requirements of MIL-STD-750, MIL-STD-202, and MIL-STD-883.

## **ESD Rating**

PIN Diodes are susceptible to ESD conditions as with all semiconductors. The ESD rating for these devices is Class 0, HBM.



Document No. DS12635, Rev. A Revision Date: 6/3/09



# MLM2060-300 & MLM2060-301 Electrical Specifications @ Zo = 50 $\Omega$ , TA=+ 25 °C ( Unless Otherwise Defined )

Parameter	Symbol	Units	Test Conditions	Minimum Value	Typical Value	Maximum Value
Frequency	F	GHz	Swept Frequency		2 - 6	
Insertion Loss	ΙL	dB	Swept Frequency Po = 0 dBm		-0.85	-1.1
Return Loss	R <sub>L</sub>	dB	Swept Frequency Po = 0 dBm	-13	-14	
Input Compression Power	P1dB	dBm	Swept Frequency	+7	+8	+10
2nd Harmonic	2F <sub>0</sub>	dBc	Po = 0 dBm F = 4 GHz	45	50	
Peak Incident Power	P <sub>inc</sub> (Pk)	dBm	RF Pulse Width = 1µS, 0.001 duty		+50	+51
C.W. Incident Power	P <sub>inc</sub> (CW)	dBm	Swept Frequency		+35	+36
Flat Leakage Power	P <sub>f</sub>	dBm	+50 dBm, RF Pulse Width = 1µS, 0.001 duty		+18	+20
Spike Leakage Energy	E <sub>S</sub>	Ergs	+50 dBm, RF Pulse Width = 1μS, 0.001 duty		0.1	0.2
Recovery Time	T <sub>r</sub>	ηS	( 50% Trailing RF Pulse – 1dB IL)		100	150

## **Part Number Ordering Information:**

2

Part Number	Packaging	
MLM2060-300-T	Tube	
MLM2060-300-R	Tape-Reel	
MLM2060-301-T	Tube	
MLM2060-301-R	Tape-Reel	



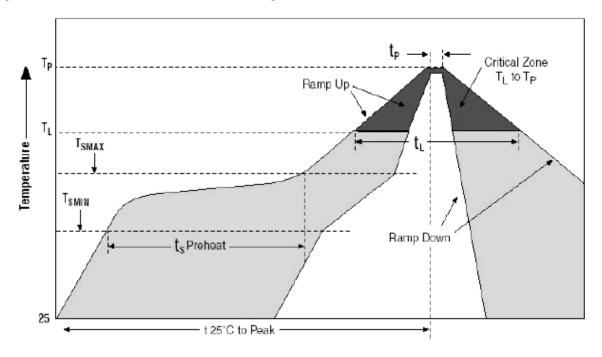
## **Assembly Instructions**

The MLM2060-300 and MLM2060-301 Limiter Series is capable of being placed onto circuit boards with pick and place manufacturing equipment from tube, tape-reel, or wafflepack dispensing. The devices are attached to the circuit using conventional solder re-flow or wave soldering procedures with RoHS type or Sn 63 / Pb 37 type solders.

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly	
Average ramp-up rate (T <sub>L</sub> to T <sub>P</sub> )	3°C/second maximum	3°C/second maximum	
Preheat - Temperature Minimum (T <sub>SMIN</sub> ) - Temperature Maximum (T <sub>SMAX</sub> ) - Time (Minimum to maximum) (t <sub>S</sub> )	100°C 150°C 60-120 seconds	150°C 200°C 60-180 seconds	
T <sub>SMAX</sub> to T <sub>L</sub> - Ramp-up Rate		3°C/second maximum	
Time Maintauined above: - Temperature (T <sub>L</sub> ) - Time (t <sub>L)</sub>	183°C 60-150 seconds	217°C 60-150 seconds	
Peak Temperature (T <sub>P</sub> )	225 +0 / -5°C	245 +0/-5°C	
Time within 5°C of actual Peak Temperature (T <sub>P</sub> )	10-30 seconds	20-40 seconds	
Ramp-down Rate	6°C/second maximum	6°C/second maximum	
Time 25°C to Peak Temperature	6 minutes maximum	8 minutes maximum	



**Graph1: Solder Re-Flow Time-Temperature Function** 

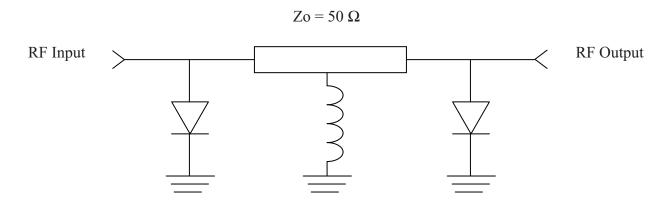


# Absolute Maximum Ratings @ $T_A = +$ 25 °C ( Unless Otherwise Defined )

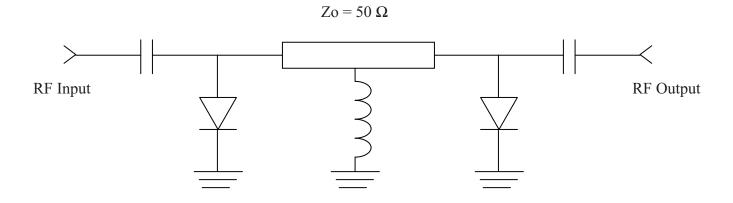
Parameter	Absolute Maximum Value	
Operating Temperature	-65 °C to +125 °C	
Storage Temperature	-65 °C to +150 °C	
Junction Temperature	+175 °C	
RF C.W. Incident Power @ + 85 °C Source & Load VSWR < 1.2:1	+35 dBm	
RF Peak. Incident Power @ + 85 °C Source & Load VSWR < 1.2:1	$+$ 50 dBm, RF Pulse Width $=$ 1 $\mu$ S, 0.001 duty cycle	
Insertion Loss Rate of Change with Operating Temperature	- 0.0025 dB / ° C	
Assembly Temperature	+260 °C for 10 Seconds	



## MLM2060-300 Limiter Schematic



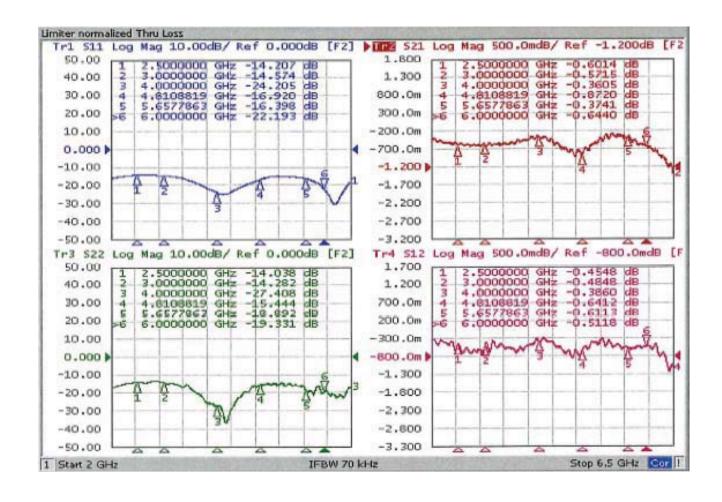
## MLM2060-301 Limiter Schematic





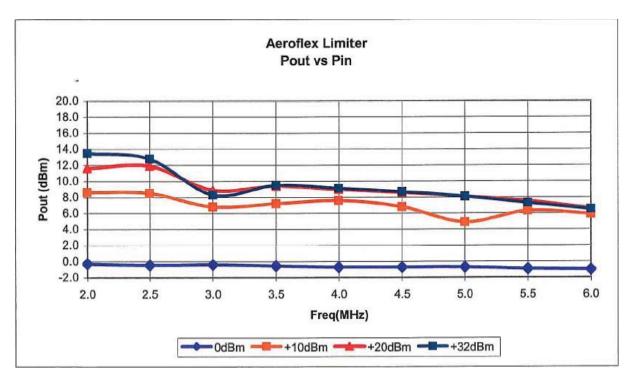


## MLM2060-300 Typical RF Small Signal Performance @ +25 °C

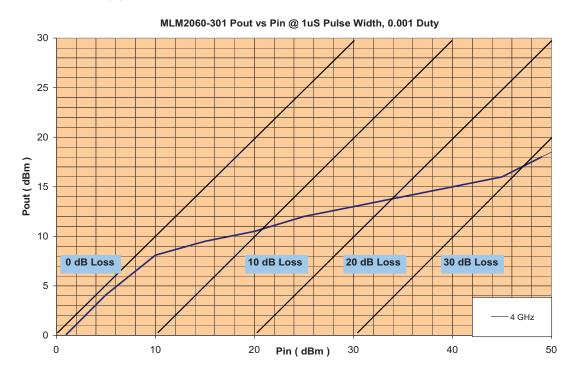




## MLM2060-300 Typical RF C.W. Incident Performance @ +25 °C

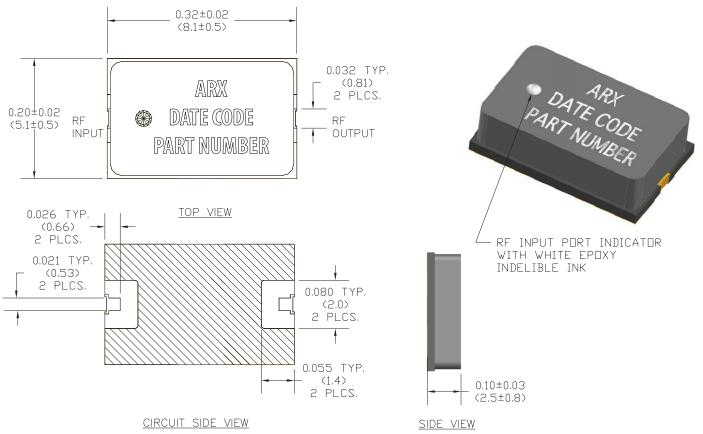


## MLM2060-301 Typical RF Peak Incident Power Performance @ +25 °C





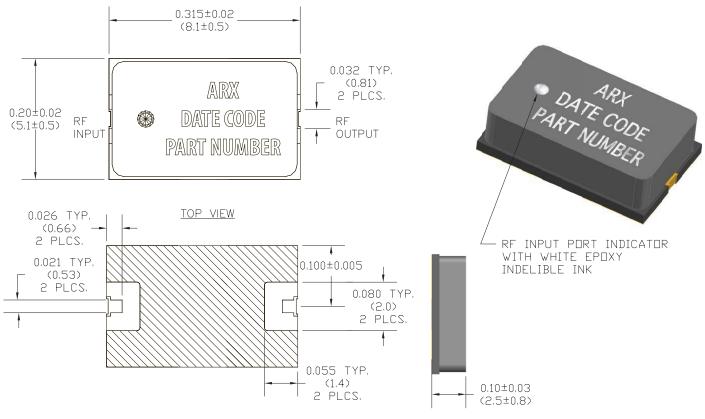
## MLM2060-300 Outline Drawing, Case Style 300, (CS300)



- NOTES: 1. SUBSTRATE MATERIAL: 20 MIL THICK ALUMINA NITRIDE (ALN) RF COVER: BLACK
- CERAMIC.
  TOP SIDE AND BACKSIDE METALLIZATION:
  100 \( \mu\) IN. TYPICAL PLATED Au OVER
- 3. DIMENSION IN PARENTHESIS ARE IN MM.



## MLM2060-301 Outline Drawing Case Style 301, (CS301)



#### CIRCUIT SIDE VIEW

#### NOTES

- SUBSTRATE MATERIAL: 20 MIL THICK ALUMINA NITRIDE (ALN) RF COVER: BLACK CERAMIC.
   TOP SIDE AND BACKSIDE METALLIZATION:
- 2. TOP SIDE AND BACKSIDE METALLIZATION
  100 µ IN. TYPICAL PLATED AU OVER
  TI-Pd
- 3. DIMENSION IN PARENTHESIS ARE IN MM.

## Aeroflex / Metelics, Inc.

#### **East Coast Operations**

54 Grenier Field Road, Londonderry, NH 03053

Tel: (603) 641-3800

Sales: (888) 641-SEMI (7364)

Fax: (603)-641-3500

#### **West Coast Operations**

975 Stewart Drive, Sunnyvale, CA 94085

Tel: (408) 737-8181 Fax: (408) 733-7645

#### www.aeroflex.com/metelics metelics-sales@aeroflex.com

Aeroflex / Metelics, Inc. reserves the right to make changes to any products and services herein at any time without notice. Consult Aeroflex or an authorized sales representative to verify that the information in this data sheet is current before using this product. Aeroflex does not assume any responsibility or liability arising out of the application or use of any product or service described herein, except as expressly agreed to in writing by Aeroflex; nor does the purchase, lease, or use of a product or service from Aeroflex convey a license under any patent rights, copyrights, trademark rights, or any other of the intellectual rights of Aeroflex or of third parties.

Copyright 2009 Aeroflex / Metelics. All rights reserved.

ISO 9001:2000









Our passion for performance is defined by three attributes represented by these three icons: solution-minded, performance-driven and customer-focused.